2.5V Drive Pch+SBD MOS FET QS5U23

●Structure

Silicon P-channel MOS FET Schottky Barrier DIODE

● Features

- 1) The QS5U23 combines Pch MOS FET with a Schottky barrier diode in a TSMT5 package.
- 2) Low on-state resistance with fast switching.
- 3) Low voltage drive(2.5V)
- 4) Built-in schottky barrier diode has low forward voltage.

2.9 0.85 1.9 0.85 0.055, 0.35 0.7 0.16 (1) (2) (3) 0.16 Each lead has same dimensions Abbreviated symbol : U23

●External dimensions (Unit: mm)

TSMT5

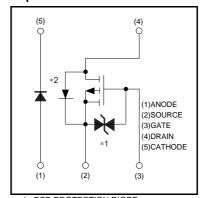
Applications

Load switch, DC/DC conversion

Packaging specifications

| Туре | Package | Taping |
|--------|------------------------------|--------|
| | Code | TR |
| | Basic ordering unit (pieces) | 3000 |
| QS5U23 | | 0 |

●Equivalent circuit



*1 ESD PROTECTION DIODE *2 BODY DIODE

●Absolute maximum ratings (Ta=25°C)

<MOSFET>

| Parameter | | Symbol | Limits | Unit | | | |
|---|------------|---------------------|-------------|-------------|--|--|--|
| Drain-source voltage | | V_{DSS} | -20 | V | | | |
| Gate-source voltage | | V _{GSS} | ±12 | V | | | |
| Drain current | Continuous | I _D | ±1.5 | A | | | |
| | Pulsed | I _{DP} *1 | ±6.0 | Α | | | |
| Source current (Body diode) | Continuous | Is | -0.75 | Α | | | |
| | Pulsed | I _{SP} *1 | -3.0 | Α | | | |
| Channel temperature | | Tch | 150 | °C | | | |
| Power dissipation | | P _D *3 | 0.9 | W / ELEMENT | | | |
| <di></di> | | | | | | | |
| Repetitive peak reverse voltage | | V _{RM} | 30 | V | | | |
| Reverse voltage | | V_R | 20 | V | | | |
| Forward current | | l _F | 0.5 | Α | | | |
| Forward current surge peak | | I _{FSM} *2 | 2.0 | Α | | | |
| Junction temperature | | Tj | 150 °C | | | | |
| Power dissipation | | P _D *3 | 0.7 | W / ELEMENT | | | |
| <mosfet and="" di=""></mosfet> | | | | | | | |
| Total power dissipation | | P _D *3 | 1.25 | W / TOTAL | | | |
| Range of Storage temperature | | Tstg | -55 to +150 | °C | | | |
| A Burdous Data analysis of Collections and Managed and a second based | | | | | | | |

^{*1} Pw≤10μs, Duty cycle≤1% *2 60Hz•1cyc. *3 Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

< MOSFET >

| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions | |
|--|--------------------|------|------|------|------|---|--|
| Gate-source leakage | Igss | _ | - | ±10 | μΑ | Vgs=±12V/ Vps=0V | |
| Drain-source breakdown voltage | V(BR)DSS | -20 | - | - | V | In=-1mA/ Vgs=0V | |
| Zero gate voltage drain current | IDSS | - | - | -1 | μΑ | VDS=-20V/ VGS=0V | |
| Gate threshold voltage | VGS(th) | -0.7 | - | -2.0 | V | VDS=-10V/ ID=-1mA | |
| | | - | 160 | 200 | mΩ | In=-1.5A, Vgs=-4.5V | |
| Static drain-source | RDS(on)* | - | 180 | 240 | mΩ | In=-1.5A, Vgs=-4V | |
| on-state resistance | | - | 260 | 340 | mΩ | ID=-0.75A, VGS=-2.5V | |
| Forward transfer admittance | Y _{fs} * | 1.0 | _ | _ | S | V _{DS} =-10V, I _D =-0.75A | |
| Input capacitance | Ciss | - | 325 | - | pF | V _D S=-10V | |
| Output capacitance | Coss | _ | 60 | - | pF | Vgs=0V | |
| Reverse transfer capacitance | Crss | _ | 40 | - | pF | f=1MHz | |
| Turn-on delay time | td(on) * | _ | 10 | - | ns | ID=-0.75A | |
| Rise Time | tr * | - | 10 | - | ns | VDD <u>=</u> −15 VGS=−4.5V RL=20Ω RG=10Ω | |
| Turn off delay time | td(off) * | - | 35 | - | ns | | |
| Fall time | tr * | - | 10 | - | ns | | |
| Total gate charge | Qg | _ | 4.2 | - | nC | V _{DD} = −15V V _{GS} =−4.5V | |
| Gate-source charge | Qgs | - | 1.0 | - | nC | | |
| Gate-drain charge | Qgd | - | 1.1 | - | nC | ID=-1.5A | |
| *Pulsed | | | | | | | |
| <body (source-drain)="" diode=""></body> | | | | | | | |
| Forward voltage | Vsd | - | - | -1.2 | V | Is=-0.75A/ Vgs=0V | |
| < Di > | | | | | | | |
| | VF | - | _ | 0.36 | V | I==0.1A | |
| Foward voltage drop | | - | - | 0.47 | V | I==0.5A | |
| Reverse current | lR | _ | _ | 100 | μА | V _R =20V | |

Electrical characteristic curves

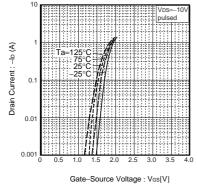
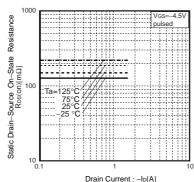


Fig.1 Typical Transfer Characteristics



Drain Current : -Io[A]
Fig.2 Static Drain-Source On-State
Resistance vs. Drain Current

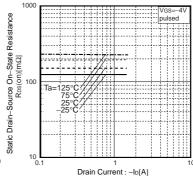


Fig.3 Static Drain-Source On-State Resistance_{VS}. Drain Current

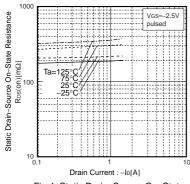


Fig.4 Static Drain–Source On–State Resistance vs. Drain–Current

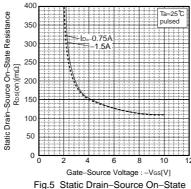
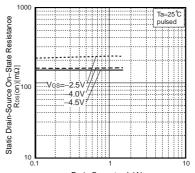


Fig.5 Static Drain-Source On-State Resistance vs.Gate-Source Voltage



Drain Current : -lo[A]
Fig.6 Static Drain-Source On-State
Resistance vs. Drain Current

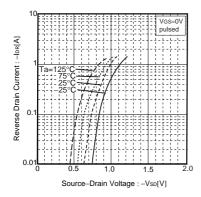


Fig.7 Reverse Drain Current VS. Source-Drain Current

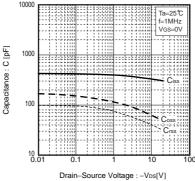


Fig.8 Typical Capactitance vs. Drain–Source Voltage

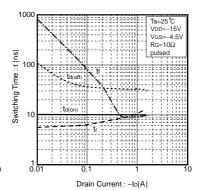


Fig.9 Switching Characteristics

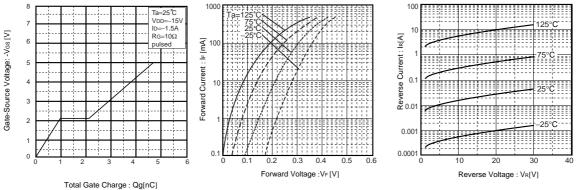


Fig.10 Dynamic Input Characteristics

Fig.11 Forward Temperature Characteristics Fig.12 Reverse Temperature Characteristics

●Measurement circuits

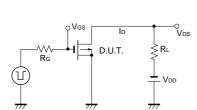


Fig.13 Switching Time Measurement Circuit

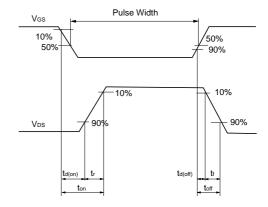


Fig.14 Switching Waveforms

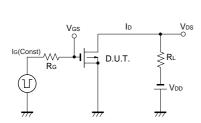


Fig.15 Gate Charge Measurement Circuit

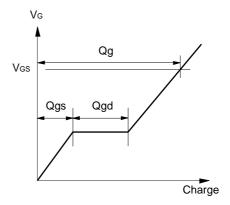


Fig.16 Gate Charge Waveforms

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